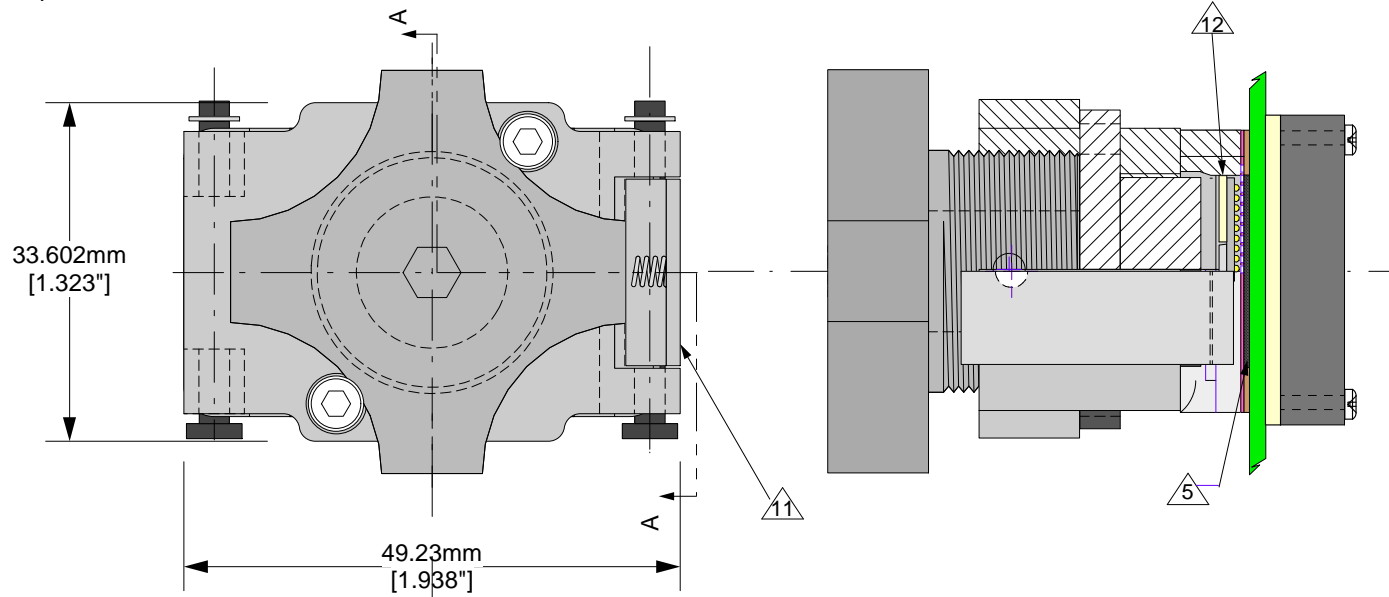
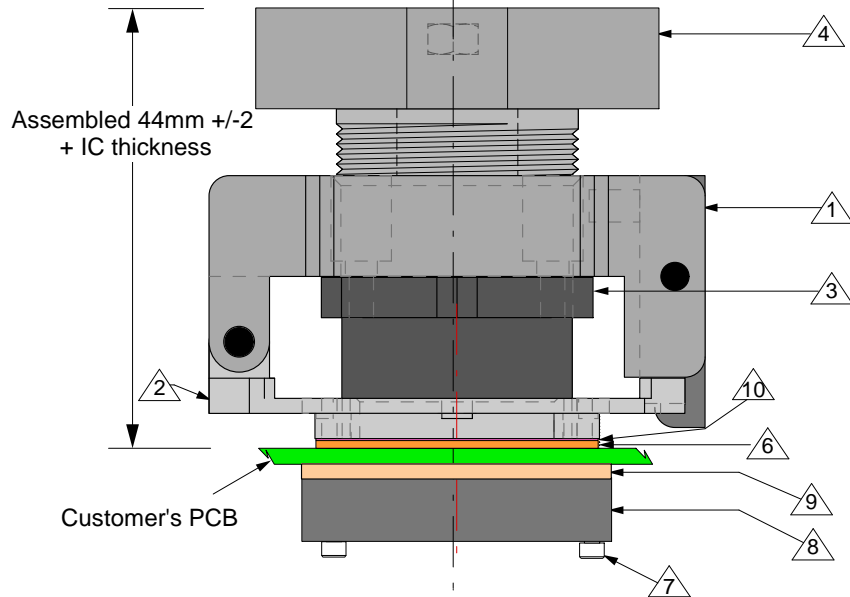


Top View



Side View
(Section AA)




Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

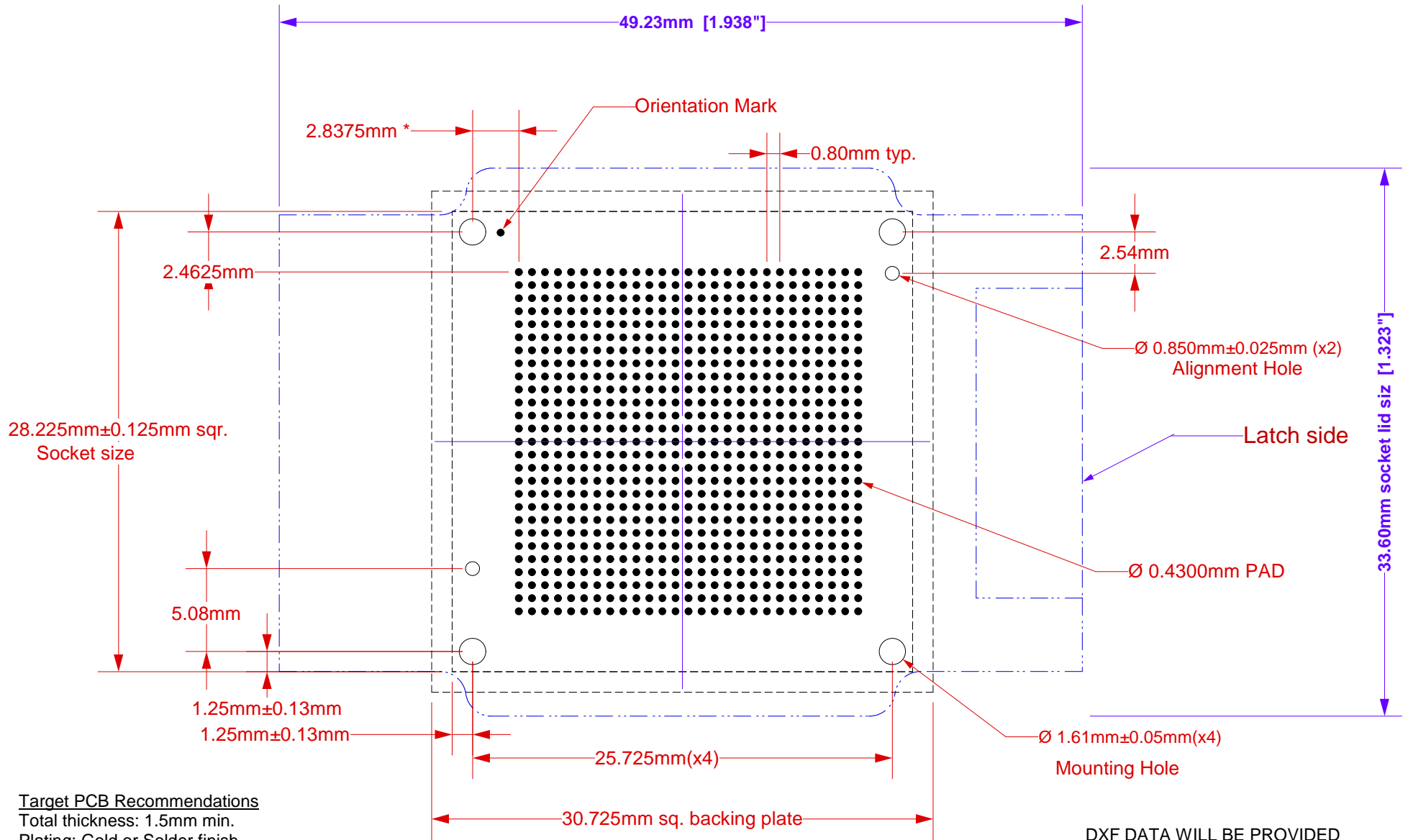
Materials:

- 1 Clam Shell Lid: Black anodized Aluminum. Height = 20 mm.
- 2 Socket Base: Black anodized Aluminum. Height = 6 mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 12 mm.
- 4 Compression Screw: Clear anodized Aluminum. Height = 27 mm, Fluted Knob
Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- 5 Elastomer Guide: Non-clad FR4. Thickness = 0.725mm.
- 6 Socket Base Screw: Socket Head Cap Screw, alloy steel with black oxide finish, 0-80 Thread, 1/2" long.
- 7 Backing Plate: Black anodized Aluminum
- 8 Insulation Plate: Ultem
- 9 Ball Guide: Kapton polyimide.
- 10 Latch: Black anodized Aluminum.
- 11 IC frame: Ultem

	CG-BGA-4007 Drawing	Status: Released	Scale: 1.25:1	Rev: A
	© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: Vinayak R	Date: 3/1/10	
		File: CG-BGA-4007 Dwg	Modified:	

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.


***Note: BGA pattern is not symmetrical with respect to the mounting holes.**



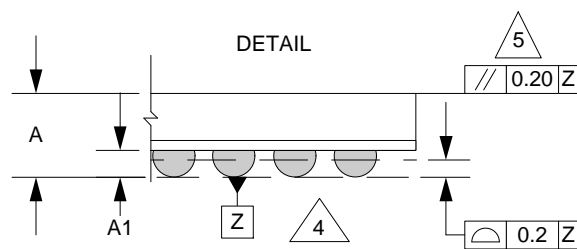
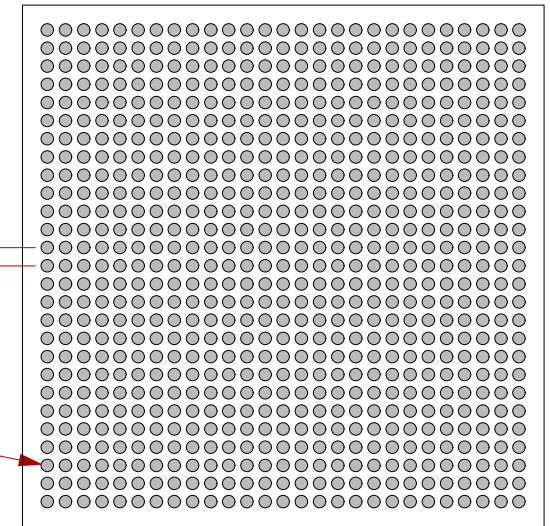
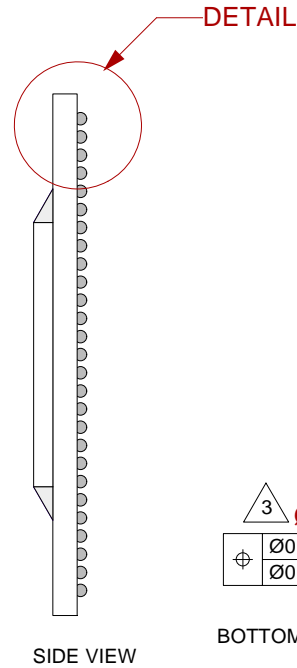
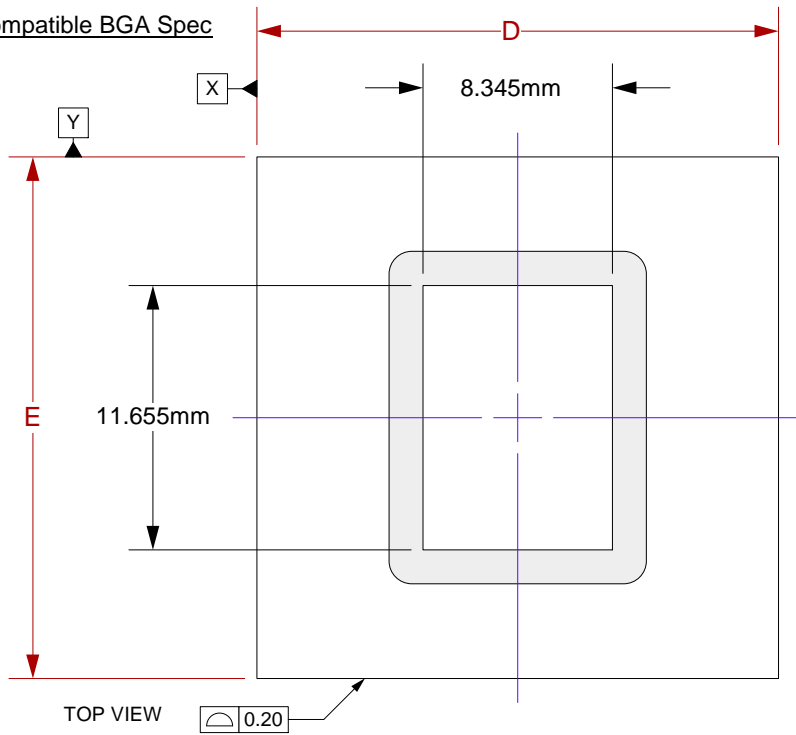
Target PCB Recommendations
Total thickness: 1.5mm min.
Plating: Gold or Solder finish

DXF DATA WILL BE PROVIDED

Recommended PCB Layout Tolerances:
±0.025mm [±0.001"] unless stated otherwise.

	CG-BGA-4007 Drawing	Status: Released	Scale: 3:1	Rev: A
	© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: Vinayak R	Date: 3/1/10	
		File: CG-BGA-4007 Dwg	Modified:	


Compatible BGA Spec



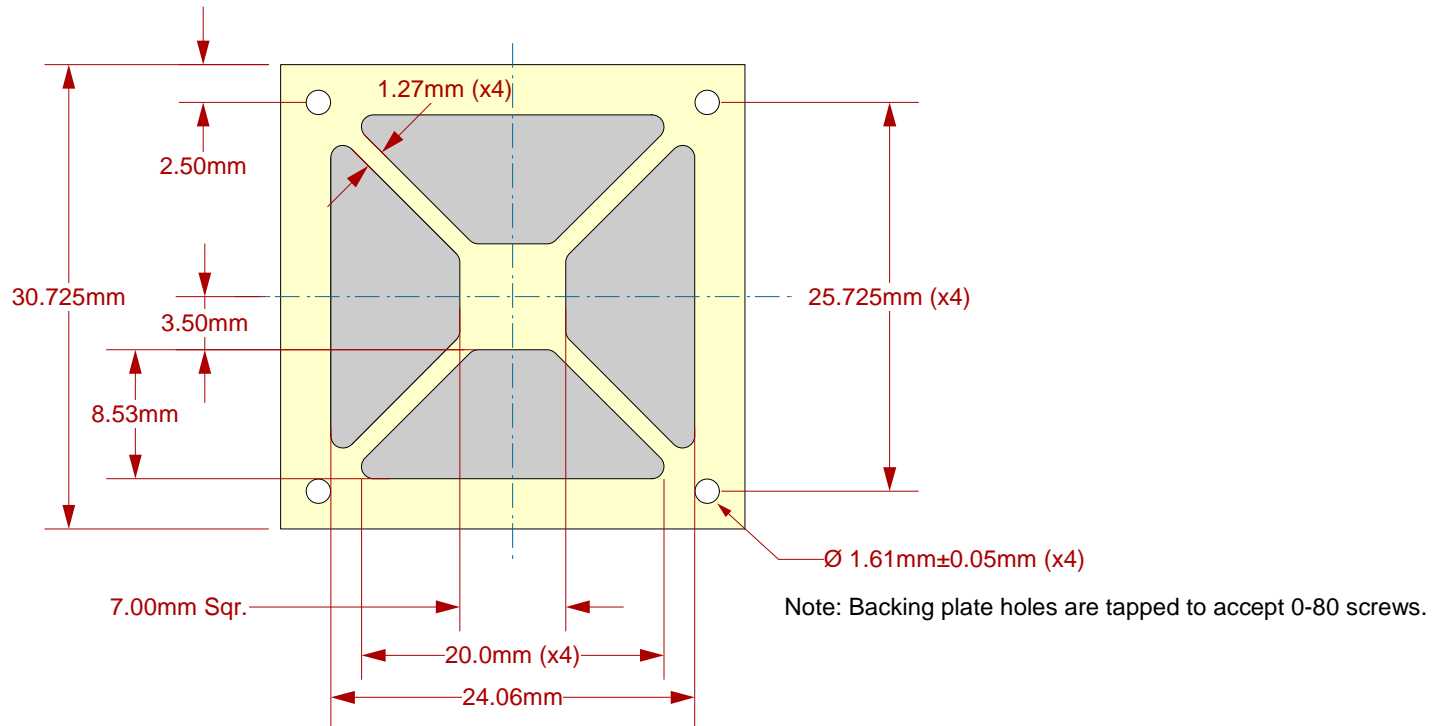
1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.15
A1	0.25	0.35
b		0.50
D	23.0 BSC	
E	23.0 BSC	
e	0.8 BSC	

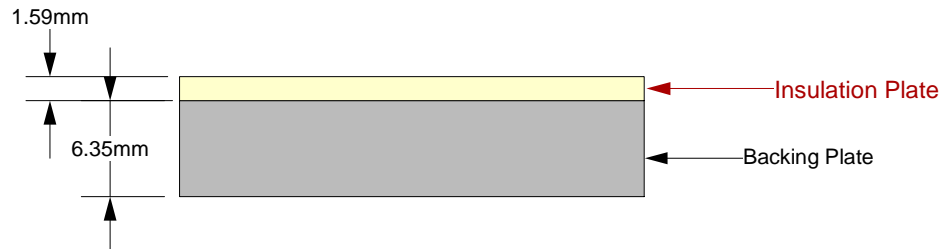
Array:27x27

 <p>CG-BGA-4007 Drawing © 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Status: Released	Scale:-	Rev: A
	Drawing: Vinayak R		Date: 3/1/10
	File: CG-BGA-4007 Dwg		Modified:


Top View



Side View

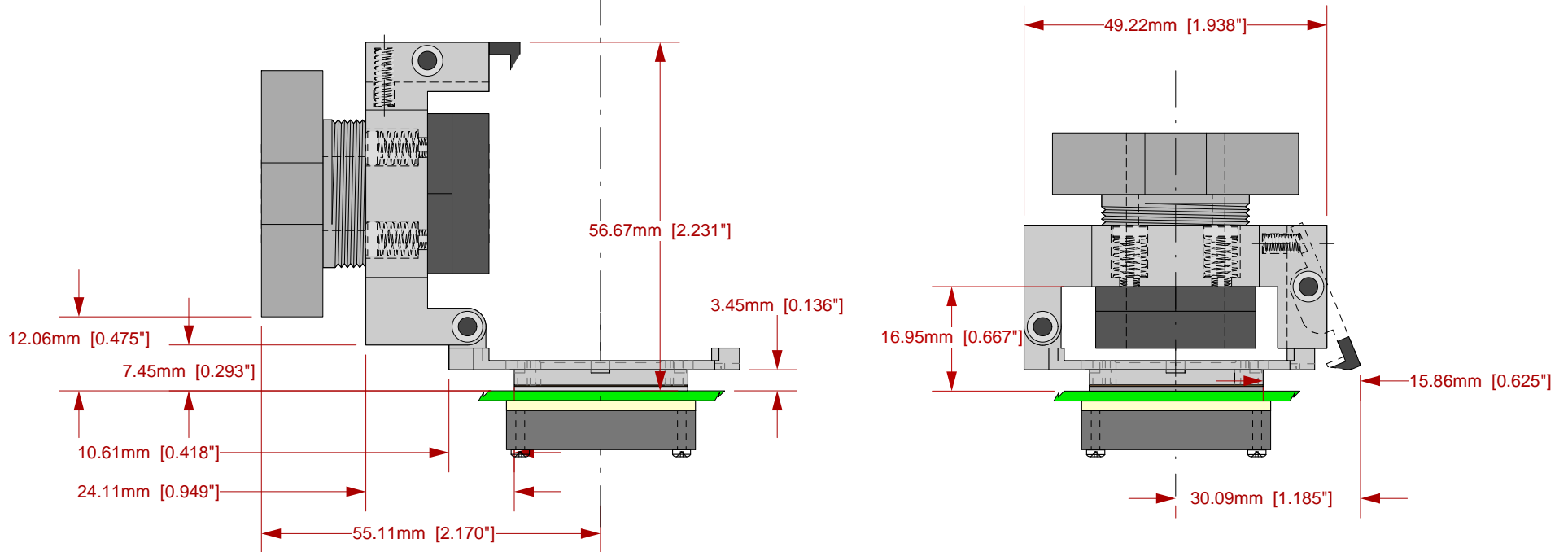
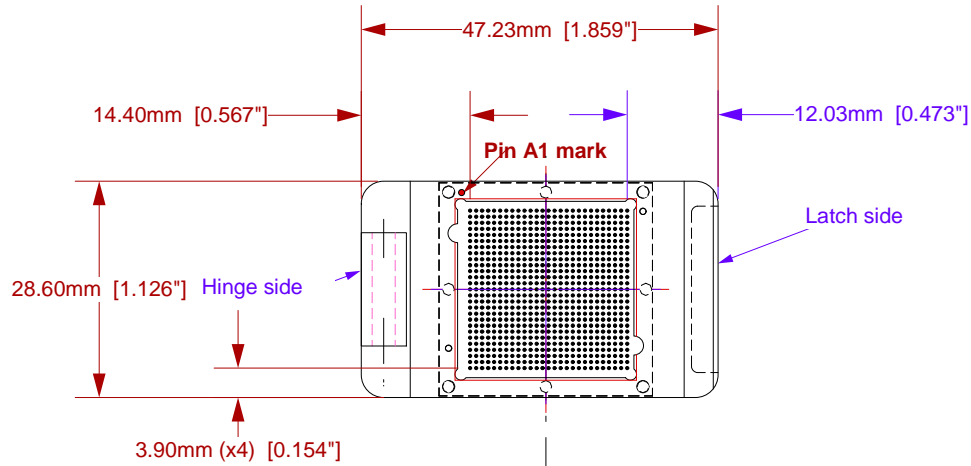


Description: Backing Plate with Insulation Plate


	CG-BGA-4007 Drawing © 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Status: Released	Scale: 2:1	Rev: A
		Drawing: Vinayak R		Date: 3/1/10
		File: CG-BGA-4007 Dwg		Modified:

All dimensions are in mm.
 All tolerances are +/- 0.125mm.
 (Unless stated otherwise)

Top View of Socket Base



Description: Backing Plate with Insulation Plate

	CG-BGA-4007 Drawing	Status: Released	Scale: 1.25:1	Rev: A
	© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: Vinayak R		Date: 3/1/10
		File: CG-BGA-4007 Dwg	Modified:	

All dimensions are in mm.
 All tolerances are +/- 0.125mm.
 (Unless stated otherwise)